



3.3V CMOS 16-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS, 5 VOLT TOLERANT I/O, BUS-HOLD

IDT74LVCH16952A

FEATURES:

- Typical $t_{sk(0)}$ (Output Skew) < 250ps
- ESD > 2000V per MIL-STD-883, Method 3015;
> 200V using machine model (C = 200pF, R = 0)
- 0.635mm pitch SSOP, 0.50mm pitch TSSOP
and 0.40mm pitch TVSOP packages
- Extended commercial range of -40°C to +85°C
- $V_{CC} = 3.3V \pm 0.3V$, Normal Range
- $V_{CC} = 2.7V$ to 3.6V, Extended Range
- CMOS power levels (0.4μW typ. static)
- All inputs, outputs and I/O are 5 Volt tolerant
- Supports hot insertion

Drive Features for LVCH16952A:

- High Output Drivers: $\pm 24mA$
- Reduced system switching noise

APPLICATIONS:

- 5V and 3.3V mixed voltage systems
- Data communication and telecommunication systems

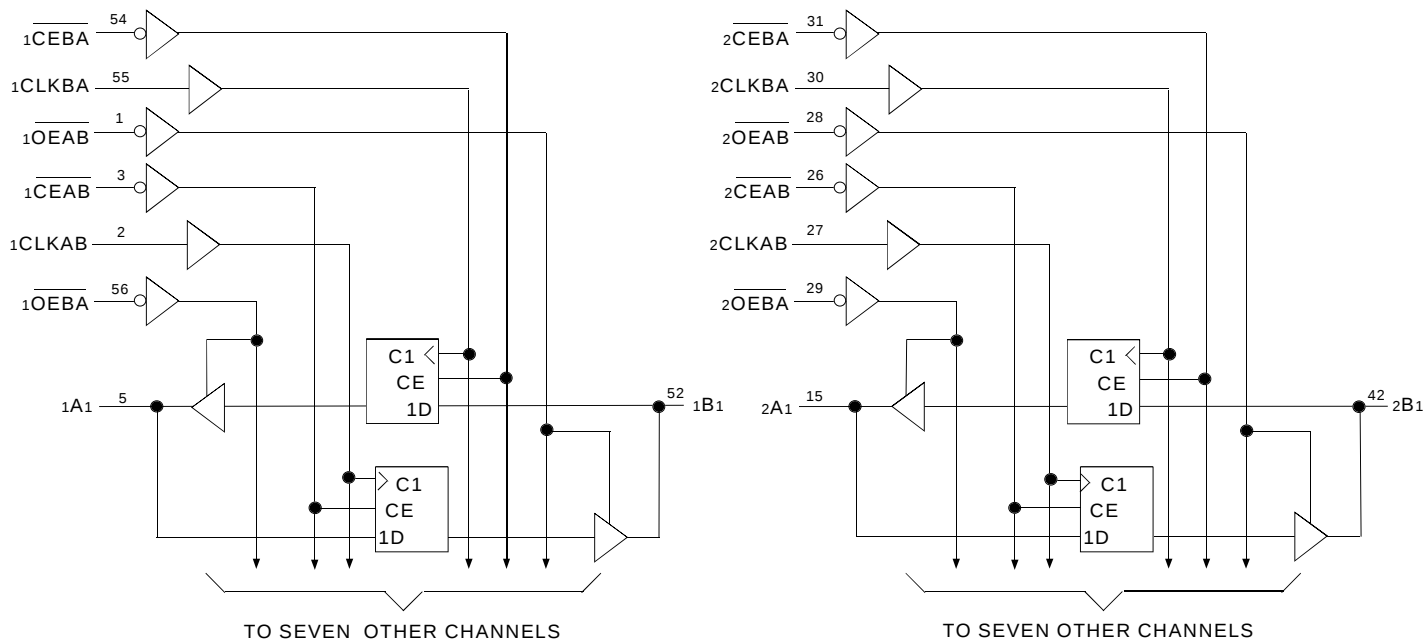
DESCRIPTION

This 16-bit registered transceiver is built using advanced dual metal CMOS technology. This high-speed, low power device is organized as two independent 8-bit D-type registered transceivers with separate input and output control for independent control of data flow in either direction. For example, the A-to-B Enable ($\overline{CEAB}$) must be LOW to enter data from the A port. $CLKAB$ controls the clocking function. When $CLKAB$ toggles from LOW-to-HIGH, the data present on the A port will be clocked into the register. $\overline{OEAB}$ performs the output enable function on the B port. Data flow from the B port to A port is similar but requires using $\overline{CEBA}$, $CLKBA$, and $\overline{OEBA}$ inputs. Full 16-bit operation is achieved by tying the control pins of the independent transceivers together.

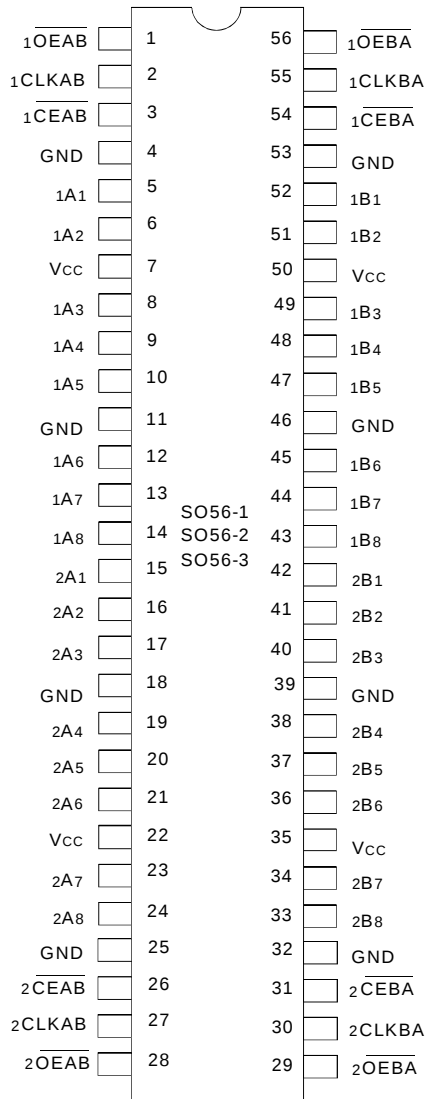
All pins can be driven from either 3.3V or 5V devices. This feature allows the use of this device as a translator in a mixed 3.3V/5V supply system.

The LVCH16952A has “bus-hold” which retains the inputs’ last state whenever the input goes to a high impedance. This prevents floating inputs and eliminates the need for pull-up/down resistors.

Functional Block Diagram



PIN CONFIGURATION



SSOP/ TSSOP/ TVSOP
TOP VIEW

PIN DESCRIPTION

Pin Names	Description
$\overline{xOEAB}$	A-to-B Output Enable Inputs (Active LOW)
$\overline{xOEBA}$	B-to-A Output Enable Inputs (Active LOW)
$\overline{xCEAB}$	A-to-B Clock Enable Inputs (Active LOW)
$\overline{xCEBA}$	B-to-A Clock Enable Inputs (Active LOW)
$xCLKAB$	A-to-B Clock Inputs
$xCLKBA$	B-to-A Clock Inputs
xAx	A-to-B Data Inputs or B-to-A 3-State Outputs ⁽¹⁾
xBx	B-to-A Data Inputs or A-to-B 3-State Outputs ⁽¹⁾

NOTE:

- These pins have "Bus-hold". All other pins are standard inputs, outputs, or I/Os.

ABSOLUTE MAXIMUM RATINGS (1)

Symbol	Description	Max.	Unit
$V_{TERM}^{(2)}$	Terminal Voltage with Respect to GND	- 0.5 to +6.5	V
$V_{TERM}^{(3)}$	Terminal Voltage with Respect to GND	- 0.5 to +6.5	V
TSTG	Storage Temperature	- 65 to +150	°C
I _{OUT}	DC Output Current	- 50 to +50	mA
I _{IK} I _{OK}	Continuous Clamp Current, $V_I < 0$ or $V_O < 0$	- 50	mA
I _{CC} I _{SS}	Continuous Current through each V _{CC} or GND	±100	mA

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NOTES:

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- V_{CC} terminals.
- All terminals except V_{CC}.

CAPACITANCE (T_A = +25°C, f = 1.0MHz)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0V	4.5	6	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0V	6.5	8	pF
C _{I/O}	I/O Port Capacitance	V _{IN} = 0V	6.5	8	pF

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NOTE:

- As applicable to the device type.

FUNCTION TABLE (1, 2)

Inputs				Outputs
$\overline{xCEAB}$	$xCLKAB$	$\overline{xOEAB}$	xAx	xBx
H	X	L	X	B ₀
X	L	L	X	B ₀
L	↑	L	L	L
L	↑	L	H	H
X	X	H	X	Z

NOTES:

- H = HIGH Voltage Level
L = LOW Voltage Level
X = Don't Care
Z = High-Impedance
↑ = LOW-to-HIGH Transition
B₀ = Level of B before the indicated steady-state input conditions were established.
- A-to-B data flow is shown: B-to-A data flow is similar but uses $\overline{xCEBA}$, $xCLKBA$, and $\overline{xOEBA}$.

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified:

Operating Condition: $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$

Symbol	Parameter	Test Conditions		Min.	Typ. ⁽¹⁾	Max.	Unit
V_{IH}	Input HIGH Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		1.7	—	—	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		2	—	—	
V_{IL}	Input LOW Voltage Level	$V_{CC} = 2.3\text{V}$ to 2.7V		—	—	0.7	V
		$V_{CC} = 2.7\text{V}$ to 3.6V		—	—	0.8	
I_{IH} I_{IL}	Input Leakage Current	$V_{CC} = 3.6\text{V}$	$V_I = 0$ to 5.5V	—	—	± 5	μA
I_{OZH} I_{OZL}	High Impedance Output Current (3-State Output pins)	$V_{CC} = 3.6\text{V}$	$V_O = 0$ to 5.5V	—	—	± 10	μA
I_{OFF}	Input/Output Power Off Leakage	$V_{CC} = 0\text{V}$, V_{IN} or $V_O \leq 5.5\text{V}$		—	—	± 50	μA
V_{IK}	Clamp Diode Voltage	$V_{CC} = 2.3\text{V}$, $I_{IN} = -18\text{mA}$		—	-0.7	-1.2	V
V_H	Input Hysteresis	$V_{CC} = 3.3\text{V}$		—	100	—	mV
I_{CCL} I_{CCH} I_{CCZ}	Quiescent Power Supply Current	$V_{CC} = 3.6\text{V}$	$V_{IN} = \text{GND}$ or V_{CC}	—	—	10	μA
			$3.6 \leq V_{IN} \leq 5.5\text{V}^{(2)}$	—	—	10	
ΔI_{CC}	Quiescent Power Supply Current Variation	One input at $V_{CC} - 0.6\text{V}$ other inputs at V_{CC} or GND		—	—	500	μA

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NOTES:

- Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.
- This applies in the disabled state only.

BUS-HOLD CHARACTERISTICS

Symbol	Parameter ⁽¹⁾	Test Conditions		Min.	Typ. ⁽²⁾	Max.	Unit
I_{BHH} I_{BHL}	Bus-Hold Input Sustain Current	$V_{CC} = 3.0\text{V}$	$V_I = 2.0\text{V}$	-75	—	—	μA
			$V_I = 0.8\text{V}$	75	—	—	
I_{BHH} I_{BHL}	Bus-Hold Input Sustain Current	$V_{CC} = 2.3\text{V}$	$V_I = 1.7\text{V}$	—	—	—	μA
			$V_I = 0.7\text{V}$	—	—	—	
I_{BHHO} I_{BHLO}	Bus-Hold Input Overdrive Current	$V_{CC} = 3.6\text{V}$	$V_I = 0$ to 3.6V	—	—	± 500	μA

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NOTES:

- Pins with Bus-hold are identified in the pin description.
- Typical values are at $V_{CC} = 3.3\text{V}$, $+25^{\circ}\text{C}$ ambient.

OUTPUT DRIVE CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Max.	Unit
VOH	Output HIGH Voltage	V _{CC} = 2.3V to 3.6V	I _{OH} = – 0.1mA	V _{CC} – 0.2	—	V
		V _{CC} = 2.3V	I _{OH} = – 6mA	2	—	
		V _{CC} = 2.3V	I _{OH} = – 12mA	1.7	—	
		V _{CC} = 2.7V		2.2	—	
		V _{CC} = 3.0V		2.4	—	
		V _{CC} = 3.0V	I _{OH} = – 24mA	2.2	—	
VOL	Output LOW Voltage	V _{CC} = 2.3V to 3.6V	I _{OL} = 0.1mA	—	0.2	V
		V _{CC} = 2.3V	I _{OL} = 6mA	—	0.4	
			I _{OL} = 12mA	—	0.7	
		V _{CC} = 2.7V	I _{OL} = 12mA	—	0.4	
		V _{CC} = 3.0V	I _{OL} = 24mA	—	0.55	

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NOTE:

1. V_{IH} and V_{IL} must be within the min. or max. range shown in the DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE table for the appropriate V_{CC} range. T_A = – 40°C to +85°C.

OPERATING CHARACTERISTICS, V_{CC} = 3.3V ± 0.3V, T_A = 25°C

Symbol	Parameter	Test Conditions	Typical	Unit
CPD	Power Dissipation Capacitance per Transceiver Outputs enabled	C _L = 0pF, f = 10Mhz	87	pF
CPD	Power Dissipation Capacitance per Transceiver Outputs disabled		43	pF

SWITCHING CHARACTERISTICS (1)

Symbol	Parameter	V _{CC} = 2.7V		V _{CC} = 3.3V±0.3V		Unit
		Min.	Max.	Min.	Max.	
f _{MAX}		150	—	150	—	MHz
t _{PLH} t _{PHL}	Propagation Delay xCLKAB, xCLKBA to xBx, xAx	—	7.6	1.6	6.6	ns
t _{PZH} t _{PZL}	Output Enable Time xOEBA, xOEAB to xAx, xBx	—	8	1.1	6.6	ns
t _{PHZ} t _{PLZ}	Output Disable Time xOEBA, xOEAB to xAx, xBx	—	7.1	1.9	6.7	ns
t _{SU}	Set-up Time, Data Before xCLKAB↑, xCLKBA↑	3.4	—	2.8	—	ns
t _H	Hold Time, Data After xCLKAB↑, xCLKBA↑	0.5	—	0.5	—	ns
t _{SU}	Set-up Time, xCEAB, xCEBA Before xCLKAB↑, xCLKBA↑	1.8	—	1.4	—	ns
t _H	Hold Time, xCEAB, xCEBA After xCLKAB↑, xCLKBA↑	1.1	—	1.9	—	ns
t _w	Pulse Duration, xCLKAB or xCLKBA HIGH or LOW	3.3	—	3.3	—	ns
t _{sk(0)}	Output Skew ⁽²⁾	—	—	—	1	ns

NOTES:

1. See test circuits and waveforms. T_A = – 40°C to + 85°C.
2. Skew between any two outputs of the same package and switching in the same direction.

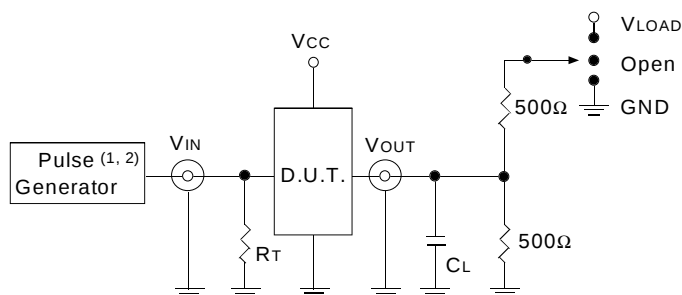
TEST CIRCUITS AND WAVEFORMS

TEST CONDITIONS

Symbol	V _{CC} (1) = 3.3V ± 0.3V	V _{CC} (1) = 2.7V	V _{CC} (2) = 2.5V ± 0.2V	Unit
V _{LOAD}	6	6	2 x V _{CC}	V
V _{IH}	2.7	2.7	V _{CC}	V
V _T	1.5	1.5	V _{CC} / 2	V
V _{LZ}	300	300	150	mV
V _{HZ}	300	300	150	mV
C _L	50	50	30	pF

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TEST CIRCUITS FOR ALL OUTPUTS



DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{OUT} of the Pulse Generator.

NOTE:

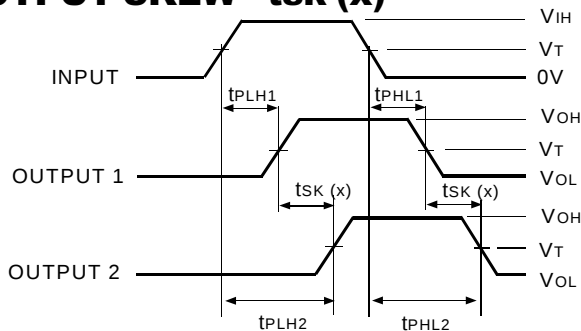
1. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_r ≤ 2.5ns; t_r ≤ 2.5ns.
2. Pulse Generator for All Pulses: Rate ≤ 10MHz; t_r ≤ 2ns; t_r ≤ 2ns.

SWITCH POSITION

Test	Switch
Open Drain	V _{LOAD}
Disable Low	
Enable Low	
Disable High	GND
Enable High	
All Other tests	Open

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OUTPUT SKEW - t_{SK}(x)



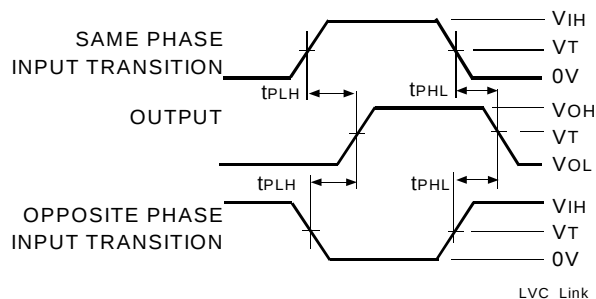
$$t_{SK}(x) = |t_{PLH2} - t_{PLH1}| \text{ or } |t_{PHL2} - t_{PHL1}|$$

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NOTES:

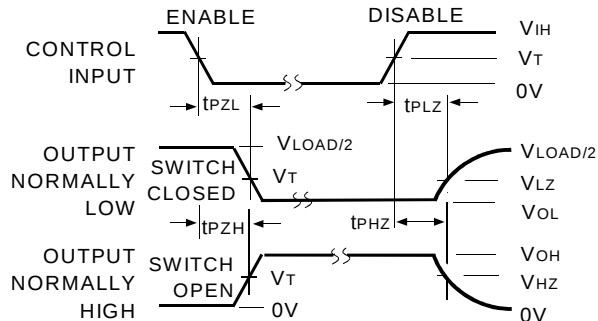
1. For t_{SK}(o) OUTPUT1 and OUTPUT2 are any two outputs.
2. For t_{SK}(b) OUTPUT1 and OUTPUT2 are in the same bank.

PROPAGATION DELAY



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ENABLE AND DISABLE TIMES

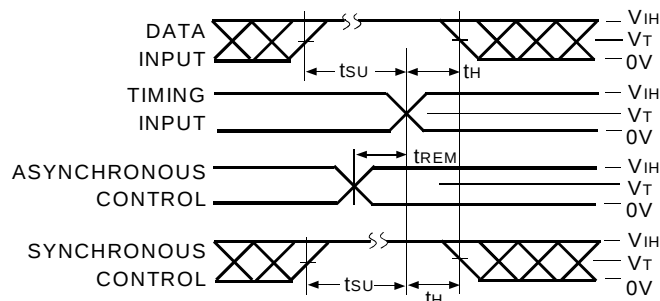


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NOTE:

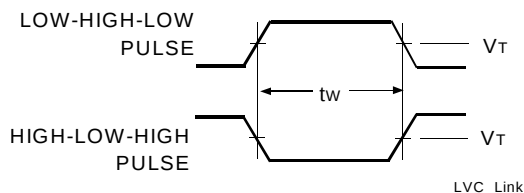
1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH.

SET-UP, HOLD, AND RELEASE TIMES



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PULSE WIDTH



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ORDERING INFORMATION

IDT	XX	LVC	X	XX	XXXX	XX	
Temp. Range	Bus-Hold	Family	Device Type	Package			
						PV	Shrink Small Outline Package (SO56-1)
						PA	Thin Shrink Small Outline Package (SO56-2)
						PF	Thin Very Small Outline Package (SO56-3)
						952A	16-Bit Registered Transceiver with 3-State Outputs
						16	Double-Density with Resistors, $\pm 24\text{mA}$
						H	Bus-hold
						74	-40°C to $+85^{\circ}\text{C}$



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